



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Perez, Erasmo; Roman, David T.
Assignee: Amkor Technology, Inc.
Title: Semiconductor Package With Exposed Die Pad And Body-Locking Leadframe
Serial No.: 09/436,158 Filing Date: November 9, 1999
Examiner: (N/A) Group Art Unit: (N/A)
Docket No.: M-7744 US

Newport Beach, California
March 2, 2001

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Please enter the following Amendment in the above-identified Application before examination thereof.

AMENDMENT

In the Specification:

Page 5, revise ¶ beginning at line 13 to read as follows:

“A locking pad is coined into an outer end portion of each lead adjacent to the frame, a wire bonding pad is coined into an inner end portion of each lead adjacent to the die pad, and a recessed shoulder is coined into the lower surface of the die pad around a central portion thereof. The wire bonding pads increase the area of the leads adjacent to

wire bonding pads, and recessed shoulder provide locking steps in the leadframe and increase the area of adhesion between the leadframe and an over-molded plastic body to lock the